



Form Type	Distribute	Version	2.0	Ref	IPC 1752A	Sectionals	Manufacturing Info/ Material Info	Subsectionals	D, A
Supplier Information									
Company Name	TE Connectivity	Request Document ID		Contact Name	Chan, Nelson	Contact Title	Manager Sales, HKG SELL DIR-EMS		
Company Unique ID	TE Connectivity	Response Date	2017-05-18	Contact Email	nelson.chan@te.com				
Contact Phone Number	852-2738-8751								
Legal Statement									
Supplier Acceptance	true								
Legal Statement									
The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.									
Product									
Manufacturer Item number	1775469-6	Amount	770.0	Version	-	Identity			
Manufacturer Item Name	HPI CONN., 2.0mm, R/A, SMT, 6P, 80u"	Weight Uom	mg	Mfr Site		Authority			
Date		UOM	Each						
EUROHS-0508	Product(s) meets EU RoHS requirement without any exemptions								
ChinaRoHS-0508	Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products								
EUREACH-0616	REACH Candidate Substances of Very High Concern ARE NOT Yet Reviewed								
Complex Article Description	REACH Candidate Substances of Very High Concern according to Once an Article Always an Article are Not Yet Reviewed								
Manufacturing Information									
J-STD-020 MSL Rating		Max Total a Wave Time		Ramp Rate		Wave Additional Info			
Classification Temp		Max Wave Solder Time	0.0	Ramp Down Rate		Psi Rating Reflow			
Max Time Within 5		Psi Rating Wave		Package Designator		Size	0.0		
Time Above 217		Reflow Additional Info		Preheat Max Temp		Terminal Base Alloy	Not Applicable		
Preheat Duration		bulk Solder Termination	Not Applicable	Nbr or Reflow Cycles		Terminal Plating	Not Applicable		
Preheat Min Temp		Nbr of Instances	0	Component Temp Spike		Shape	Not Applicable		
Product Disclosure									
Sub-Item/Material/Substance	Level	Name	Substance Category	Substance CAS	Substance Concentration	Quantity	Mass per Unit	UOM	Exemption
Material	1	Contact-Tin				1.0	10.0	mg	
Substance	2	Tin	Supplier	7440-31-5	99.98	1.0	9.998	mg	
Substance	2	Copper	Supplier	7440-50-8	0.02	1.0	0.0020	mg	
Material	1	Contact-Ni				1.0	10.0	mg	
Substance	2	Nickel	Nickel	7440-02-0	100.0	1.0	10.0	mg	
Material	1	Solder Tab-Bronze C2680				1.0	110.0	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.03	1.0	0.033	mg	
Substance	2	Zinc	Supplier	7440-66-6	34.44	1.0	37.884	mg	
Substance	2	Iron	Supplier	7439-89-6	0.03	1.0	0.033	mg	
Substance	2	Copper	Supplier	7440-50-8	65.5	1.0	72.05	mg	
Material	1	Housing-NYLON 9T				1.0	490.0	mg	
Substance	2	Benzene, ethenyl-, ar-bromo derivs., homopolymers	Supplier	148993-99-1	20.0	1.0	98.0	mg	
Substance	2	1,4-Benzenedicarb oxylc acid, polymer with 2-methyl-1,8-octanediamine and 1,9-nonanediamine	Supplier	169284-22-4	40.0	1.0	196.0	mg	

Substance	2	Glass, oxide, chemicals	Supplier	65997-17-3	36.0	1.0	176.4	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0217	4.0	1.0	19.6	mg	
Material	1	Contact-Bronze C2680				1.0	150.0	mg	
Substance	2	Zinc	Supplier	7440-66-6	34.44	1.0	51.66	mg	
Substance	2	Copper	Supplier	7440-50-8	65.5	1.0	98.25	mg	
Substance	2	Iron	Supplier	7439-89-6	0.03	1.0	0.045	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.03	1.0	0.045	mg	